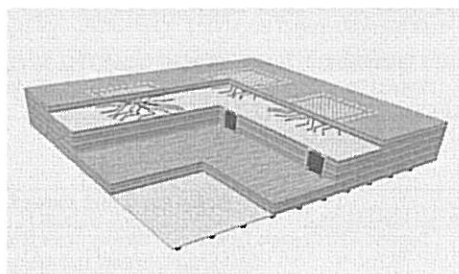


IMAPS/ACerS 5th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)

THE CURTIS HOTEL
DENVER, COLORADO - USA
APRIL 21 - 23, 2009



FINAL PROGRAM

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CICMT Program Outline		
Tuesday, April 21		
Registration		
7:30 am – 7:30 pm	Exhibit Hours	
10:00 am - 7:30 pm	Exhibit Hours	
8:30 am – 9:00 am	Keynote Presentation Title: Development of an H/LTCC-Based HPLC (High Pressure Liquid Chromatography) Microfluidic Consumable Speaker: Geoff Gerhardt, Waters Corporation	
9:00 am – 9:30 am	Keynote Presentation Title: Advanced Electro-Ceramics: Present and Future Prospect Speaker: Y. Sakabe, Murata Manufacturing Co., Ltd.	
9:30 am – 10:00 am	Keynote Presentation Title: LTCC - Technology: A Challenging Platform for Microsystem Fabrication Speaker: Walter Smetana, Vienna University of Technology	
10:00 am – 10:30 am	Break in Exhibit Hall	
	Ceramic Micro Systems Track	Ceramic Interconnect Track
Topical Sessions: 10:30 am - 12:10 pm	Session TA1: Deposition Techniques, ALD, Molecular Deposition, Aerosol Deposition Chairs: Y. C. Lee, University of Colorado at Boulder; Alexander Michaelis, Fraunhofer Institute for Ceramic Technologies and Systems	Session TA2: Direct Write Technology Chairs: Christopher A. Apple, Sandia National Laboratories; Seung-Hyun Kim, INOSTEK Inc.
12:10 pm - 1:40 pm	Lunch in Exhibit Hall (Lunch served 12:10 pm - 1:10 pm)	
Topical Session: 1:40 pm - 3:20 pm	Session TP1: Ceramic Actuators in Microsystems (Piezoelectrics Materials and Devices) Chairs: Richard Eitel, University of Kentucky; Fred Barlow, University of Idaho	
3:20 pm - 3:50 pm	Break in Exhibit Hall	
Topical Session: 3:50 pm - 5:50 pm	Session TP2: Microsystems Materials and Properties Chairs: Donald Plumlee, Boise State University; Charles Lewinsohn, Ceramtec, Inc.	Session TP3: Electromagnetic Properties Characterization Chairs: Yoshihiko Imanaka, Fujitsu Limited; Minoru Osada, National Institute for Materials Science
6:00 pm - 7:30 pm	Reception in Exhibit Hall	
Wednesday, April 22		
Registration		
Exhibit Hours		
7:30 am - 5:00 pm	Exhibit Hours	
10:00 am - 4:00 pm	Exhibit Hours	
8:30 am - 10:00 am	Session WA1: International Session on Microsystems Chairs: Leszek Golonka, Wroclaw University of Technology; Karl-Heinz Drüe, Technical University of Ilmenau	
10:00 am - 10:30 am	Break in Exhibit Hall	
Topical Sessions: 10:30 am - 11:50 am	Session WA2: Design and Fabrication of Ceramic Microsystems and Devices Chairs: Torsten Rabe, Federal Institute for Materials Research and Testing (BAM); Thomas Maeder, Ecole Polytechnique Fédérale de Lausanne	Session WA3: Processing and Design of Integrated Passives in LTCC Chair: Jerry Aguirre, Kyocera America Inc.
12:00 pm - 1:20 pm	Lunch in Exhibit Hall	
1:30 pm - 3:30 pm	Session WP1: Interactive Forum (Poster Session) One-on-One Interactive Forum. This is your chance for detailed interaction with authors whose work is too good to miss. Chair: Amy Moll, Boise State University	
3:30 pm - 4:00 pm	Break in Exhibit Hall	
4:00 pm - 5:30 pm	Session WP2: LTCC Standards Chairs: Howard Imhof, Metalor Technologies USA; Michael Ehlert, Barry Industries Inc.	
Thursday, April 23		
Registration		
7:30 am - Noon	Registration	
Topical Sessions: 8:30 am - 10:30 am	Session THA1: Advanced Packaging Technology Chairs: Martin Oppermann, EADS Deutschland GmbH; Ken Peterson, Sandia National Laboratories	
10:30 am - 12:00 pm	Session THA2: LTCC University Consortium Meeting Chairs: W. Kinzy Jones, Florida International University; Amy Moll, Boise State University	
12:00 pm	Conference Closing Remarks	
Thursday, April 23: See inside program for more information on the following...		
IEEE LTCC Standards Working Group (P1787): 8:30 am - 12:00 pm		
NIST Dielectric Measurement Tutorial: 1:30 pm - 4:00 pm		



Message from the General Co-Chairs

Welcome to the 5th International Conference on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)!

CICMT, THE premier global forum on ceramic interconnect and ceramic microsystems, continues to benefit from the complementary interests, strengths, leadership, and joint sponsorship of the International Microelectronics And Packaging Society (IMAPS) and The American Ceramic Society (ACerS). This collaboration, in two of the fastest growing areas of ceramic technology, attracts the participation of leading scientists and engineers from esteemed universities, prestigious national laboratories, and the commercial leaders in the industry.

Back in Denver after a successful meeting in Munich, Germany last year, this event brings together experts from Asia, Europe, and North and South America to present and discuss the latest advances in ceramic interconnect and ceramic microsystems technologies. Coming from more than 40 different organizations including universities as well as industry and government laboratories, the conference will provide a wide spectrum of interests reflected in the papers throughout 12 sessions. This year's keynote and international session speakers will focus on multilayer ceramic components and future applications.

In addition to the Microsystems and Ceramic Integration paths, we are delighted to add a Low Temperature Co-fired Ceramic Processing (LTCC) standards session to promote industrial interactions.

We thank the Technical Program Co-chairs Amy Moll (Boise State University), Jens Müller (Technical University Ilmenau) and Takaaki Tsurumi (Tokyo Institute of Technology); all the Session Chairs for the long hours and hard work they contributed in creating this outstanding program. Our special thanks go out to the staffs and Executive Committees of IMAPS and ACerS, who provided the steady encouragement, excellent assistance, and expert coordination to help make CICMT 2009 a reality. Finally, we thank each and every one of you for contributing to the success of CICMT 2009 through your participation and attendance. We hope that you gain as much from this conference as we have in pulling it together.

Plans are already underway for CICMT 2010 in Chiba, Japan. We welcome your comments, suggestions, and assistance to help us achieve the CICMT goal of accelerating the research, development, and product impact of our exciting ceramic technology thrusts. Please visit our website at www.cicmt.org for information on future events.

Michael Lanagan and Jun Akedo
General Co-Chairs